

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT5059635

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	ZVI OR-BACH	06/27/2018
	DEEPAK SEKAR	06/27/2018
	BRIAN CRONQUIST	06/27/2018
RECEIVING PARTY DATA		
Name:	MonolithIC 3D Inc.	
Street Address:	3555 Woodford Drive	
City:	San Jose	
State/Country:	CALIFORNIA	
Postal Code:	95124	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	16004404	
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Email:	Brian@MonolithIC3D.com	
Correspondent Name:	BRIAN CRONQUIST	
Address Line 1:	3555 WOODFORD DRIVE	
Address Line 4:	SAN JOSE, CALIFORNIA 95124	
ATTORNEY DOCKET NUMBER:	BR6CON6-CD	
NAME OF SUBMITTER:	BRIAN CRONQUIST	
SIGNATURE:	/bc/	
DATE SIGNED:	07/20/2018	
Total Attachments: 3		
source=ASMNT_Br6con6_Brian#page1.tif		
source=ASMNT_Br6con6-cd_Deepak#page1.tif		
source=ASMNT_Br6con6-cd_Zvi#page1.tif		

ASSIGNMENT

Whereas, I, **Brian Cronquist** (hereinafter referred to as Assignor(s)), residing in **San Jose, California**; have made a certain invention, and executed United States Patent Application entitled:

A 3D SEMICONDUCTOR DEVICE

as described in U.S. Patent Application Serial No. 16/004,404 and filed on 06/10/2018; and

Whereas, Monolithic 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 27 June 18

(Brian

First Name

Middle Initial

Cronquist)

Last Name

ASSIGNMENT

Whereas, I, **Deepak Sekar** (hereinafter referred to as Assignor(s)), residing in **San Jose, California**; have made a certain invention, and executed United States Patent Application entitled:

A 3D SEMICONDUCTOR DEVICE

as described in U.S. Patent Application Serial No. 16/004,404 and filed on 06/10/2018; and

Whereas, MonolithIC 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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Signed and Sealed:

INVENTOR:

DATE on

27 June 18

(Deepak

First Name

Middle Initial

Sekar)

Last Name

PATENT

REEL: 046410 FRAME: 0656

ASSIGNMENT

Whereas, I, **Zvi Or-Bach** (hereinafter referred to as Assignor(s)), residing in **San Jose, California**; have made a certain invention, and executed United States Patent Application entitled:

A 3D SEMICONDUCTOR DEVICE

as described in U.S. Patent Application Serial No. 16/004,404 and filed on 06/10/2018; and

Whereas, MonolithIC 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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Signed and Sealed:

INVENTOR:

DATE on

6-27-18

(Zvi

First Name

Middle Initial

Or-Bach)

Last Name